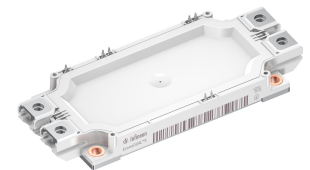


Final datasheet

EconoDUAL™3 module with TRENCHSTOP™ IGBT7 and emitter controlled 7 diode and NTC

Features

- Electrical features
 - $V_{CES} = 1700\text{ V}$
 - $I_{C\text{ nom}} = 300\text{ A} / I_{CRM} = 600\text{ A}$
 - Integrated temperature sensor
 - High current density
 - Low $V_{CE,\text{sat}}$
 - Overload operation up to 175°C
 - TRENCHSTOP™ IGBT7
 - $V_{CE,\text{sat}}$ with positive temperature coefficient
 - Suitable Infineon gate drivers can be found under <https://www.infineon.com/gdfinder>
- Mechanical features
 - High power density
 - Isolated base plate
 - PressFIT contact technology
 - Standard housing



Potential applications

- High-power converters
- Medium-voltage converters
- Motor drives
- Wind turbines

Product validation

- Qualified for industrial applications according to the relevant tests of IEC 60747, 60749 and 60068

Description

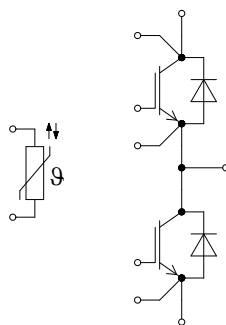


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1 Package

Table 1 Insulation coordination

Parameter	Symbol	Note or test condition	Values	Unit
Isolation test voltage	V_{ISOL}	RMS, $f = 50$ Hz, $t = 1$ min	3.4	kV
Material of module baseplate			Cu	
Internal isolation		basic insulation (class 1, IEC 61140)	Al_2O_3	
Creepage distance	d_{Creep}	terminal to heatsink	15.0	mm
Creepage distance	d_{Creep}	terminal to terminal	13.0	mm
Clearance	d_{Clear}	terminal to heatsink	12.5	mm
Clearance	d_{Clear}	terminal to terminal	10.0	mm
Comparative tracking index	CTI		> 200	
Relative thermal index (electrical)	RTI	housing	140	°C

Table 2 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Stray inductance module	L_{sCE}			20		nH
Module lead resistance, terminals - chip	$R_{CC'+EE'}$	$T_C = 25$ °C, per switch		0.8		mΩ
Storage temperature	T_{stg}		-40		125	°C
Mounting torque for module mounting	M	- Mounting according to valid application note	M5, Screw	3	6	Nm
Terminal connection torque	M	- Mounting according to valid application note	M6, Screw	3	6	Nm
Weight	G			345		g

2 IGBT, T1 / T2

Table 3 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Collector-emitter voltage	V_{CES}	$T_{vj} = 25$ °C	1700	V
Continuous DC collector current	I_{CDC}	$T_{vj\ max} = 175$ °C $T_C = 95$ °C	300	A
Maximum RMS module DC-terminal current	I_{tRMS}	$T_{Terminal} = 90$ °C, $T_C = 90$ °C	580	A
		$T_{Terminal} = 105$ °C, $T_C = 90$ °C	565	

(table continues...)
 Datasheet

Table 3 (continued) Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak collector current	I_{CRM}	t_p limited by $T_{vj\ op}$	600	A
Gate-emitter peak voltage	V_{GES}		±20	V

Table 4 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Collector-emitter saturation voltage	$V_{CE\ sat}$	$I_C = 300\ A, V_{GE} = 15\ V$	$T_{vj} = 25\ ^\circ C$	1.70	1.85	V
			$T_{vj} = 125\ ^\circ C$	1.95		
			$T_{vj} = 150\ ^\circ C$	2.05		
			$T_{vj} = 175\ ^\circ C$	2.10		
Gate threshold voltage	V_{Geth}	$I_C = 6.15\ mA, V_{CE} = V_{GE}, T_{vj} = 25\ ^\circ C$	5.15	5.80	6.45	V
Gate charge	Q_G	$V_{GE} = \pm 15\ V, V_{CC} = 900\ V$		2.8		μC
Internal gate resistor	R_{Gint}	$T_{vj} = 25\ ^\circ C$		0.8		Ω
Input capacitance	C_{ies}	$f = 100\ kHz, T_{vj} = 25\ ^\circ C, V_{CE} = 25\ V, V_{GE} = 0\ V$		30.6		nF
Reverse transfer capacitance	C_{res}	$f = 100\ kHz, T_{vj} = 25\ ^\circ C, V_{CE} = 25\ V, V_{GE} = 0\ V$		0.108		nF
Collector-emitter cut-off current	I_{CES}	$V_{CE} = 1700\ V, V_{GE} = 0\ V$			5	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\ V, V_{GE} = 20\ V, T_{vj} = 25\ ^\circ C$			100	nA
Turn-on delay time (inductive load)	t_{don}	$I_C = 300\ A, V_{CC} = 900\ V, V_{GE} = \pm 15\ V, R_{Gon} = 0.82\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.133		μs
			$T_{vj} = 125\ ^\circ C$	0.162		
			$T_{vj} = 150\ ^\circ C$	0.162		
			$T_{vj} = 175\ ^\circ C$	0.163		
Rise time (inductive load)	t_r	$I_C = 300\ A, V_{CC} = 900\ V, V_{GE} = \pm 15\ V, R_{Gon} = 0.82\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.025		μs
			$T_{vj} = 125\ ^\circ C$	0.030		
			$T_{vj} = 150\ ^\circ C$	0.032		
			$T_{vj} = 175\ ^\circ C$	0.033		
Turn-off delay time (inductive load)	t_{doff}	$I_C = 300\ A, V_{CC} = 900\ V, V_{GE} = \pm 15\ V, R_{Goff} = 2.4\ \Omega$	$T_{vj} = 25\ ^\circ C$	0.394		μs
			$T_{vj} = 125\ ^\circ C$	0.489		
			$T_{vj} = 150\ ^\circ C$	0.507		
			$T_{vj} = 175\ ^\circ C$	0.525		

(table continues...)

Table 4 (continued) Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Fall time (inductive load)	t_f	$I_C = 300 \text{ A}, V_{CC} = 900 \text{ V}, V_{GE} = \pm 15 \text{ V}, R_{Goff} = 2.4 \Omega$	$T_{vj} = 25 \text{ }^\circ\text{C}$		0.245	μs
			$T_{vj} = 125 \text{ }^\circ\text{C}$		0.445	
			$T_{vj} = 150 \text{ }^\circ\text{C}$		0.518	
			$T_{vj} = 175 \text{ }^\circ\text{C}$		0.590	
Turn-on energy loss per pulse	E_{on}	$I_C = 300 \text{ A}, V_{CC} = 900 \text{ V}, L_\sigma = 25 \text{ nH}, V_{GE} = \pm 15 \text{ V}, R_{Gon} = 0.82 \Omega, di/dt = 7100 \text{ A}/\mu\text{s} (T_{vj} = 175 \text{ }^\circ\text{C})$	$T_{vj} = 25 \text{ }^\circ\text{C}$		30.1	mJ
			$T_{vj} = 125 \text{ }^\circ\text{C}$		53.1	
			$T_{vj} = 150 \text{ }^\circ\text{C}$		62.3	
			$T_{vj} = 175 \text{ }^\circ\text{C}$		71.5	
Turn-off energy loss per pulse	E_{off}	$I_C = 300 \text{ A}, V_{CC} = 900 \text{ V}, L_\sigma = 25 \text{ nH}, V_{GE} = \pm 15 \text{ V}, R_{Goff} = 2.4 \Omega, dv/dt = 3700 \text{ V}/\mu\text{s} (T_{vj} = 175 \text{ }^\circ\text{C})$	$T_{vj} = 25 \text{ }^\circ\text{C}$		49.9	mJ
			$T_{vj} = 125 \text{ }^\circ\text{C}$		74.2	
			$T_{vj} = 150 \text{ }^\circ\text{C}$		83.3	
			$T_{vj} = 175 \text{ }^\circ\text{C}$		92.3	
SC data	I_{SC}	$V_{GE} = 15 \text{ V}, V_{CC} = 1000 \text{ V}, V_{CEmax} = V_{CES} - L_{sCE} \cdot di/dt$	$t_p \leq 8 \mu\text{s}, T_{vj} = 150 \text{ }^\circ\text{C}$		1100	A
			$t_p \leq 6 \mu\text{s}, T_{vj} = 175 \text{ }^\circ\text{C}$		1000	
Thermal resistance, junction to case	R_{thJC}	per IGBT			0.112	K/W
Thermal resistance, case to heat sink	R_{thCH}	per IGBT, $\lambda_{grease} = 1 \text{ W}/(\text{m}\cdot\text{K})$		0.0440		K/W
Temperature under switching conditions	T_{vjop}		-40		175	$^\circ\text{C}$

Note: $T_{vjop} > 150 \text{ }^\circ\text{C}$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

3 Diode, D1 / D2

Table 5 Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit
Repetitive peak reverse voltage	V_{RRM}	$T_{vj} = 25 \text{ }^\circ\text{C}$	1700	V
Continuous DC forward current	I_F		300	A
Repetitive peak forward current	I_{FRM}	$t_p = 1 \text{ ms}$	600	A

(table continues...)

Table 5 (continued) Maximum rated values

Parameter	Symbol	Note or test condition	Values	Unit	
I^2t - value	I^2t	$t_p = 10 \text{ ms}, V_R = 0 \text{ V}$	$T_{vj} = 125 \text{ °C}$	6000	A^2s
			$T_{vj} = 175 \text{ °C}$	4900	

Table 6 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit	
			Min.	Typ.	Max.		
Forward voltage	V_F	$I_F = 300 \text{ A}, V_{GE} = 0 \text{ V}$	$T_{vj} = 25 \text{ °C}$		2.35	2.50	V
			$T_{vj} = 125 \text{ °C}$		2.25		
			$T_{vj} = 150 \text{ °C}$		2.20		
			$T_{vj} = 175 \text{ °C}$		2.10		
Peak reverse recovery current	I_{RM}	$V_{CC} = 900 \text{ V}, I_F = 300 \text{ A}, V_{GE} = -15 \text{ V}, -di_F/dt = 7500 \text{ A}/\mu\text{s} (T_{vj} = 175 \text{ °C})$	$T_{vj} = 25 \text{ °C}$		420		A
			$T_{vj} = 125 \text{ °C}$		426		
			$T_{vj} = 150 \text{ °C}$		426		
			$T_{vj} = 175 \text{ °C}$		426		
Recovered charge	Q_r	$V_{CC} = 900 \text{ V}, I_F = 300 \text{ A}, V_{GE} = -15 \text{ V}, -di_F/dt = 7500 \text{ A}/\mu\text{s} (T_{vj} = 175 \text{ °C})$	$T_{vj} = 25 \text{ °C}$		40.2		μC
			$T_{vj} = 125 \text{ °C}$		72.2		
			$T_{vj} = 150 \text{ °C}$		85.2		
			$T_{vj} = 175 \text{ °C}$		98.2		
Reverse recovery energy	E_{rec}	$V_{CC} = 900 \text{ V}, I_F = 300 \text{ A}, V_{GE} = -15 \text{ V}, -di_F/dt = 7500 \text{ A}/\mu\text{s} (T_{vj} = 175 \text{ °C})$	$T_{vj} = 25 \text{ °C}$		24.1		mJ
			$T_{vj} = 125 \text{ °C}$		45.3		
			$T_{vj} = 150 \text{ °C}$		52.9		
			$T_{vj} = 175 \text{ °C}$		60.4		
Thermal resistance, junction to case	R_{thJC}	per diode			0.188	K/W	
Thermal resistance, case to heat sink	R_{thCH}	per diode, $\lambda_{grease} = 1 \text{ W}/(\text{m}\cdot\text{K})$		0.0529		K/W	
Temperature under switching conditions	T_{vjop}		-40		175	$^{\circ}\text{C}$	

Note: $T_{vjop} > 150 \text{ °C}$ is only allowed for operation at overload conditions. For detailed specifications please refer to AN 2018-14.

4 NTC-Thermistor

Table 7 Characteristic values

Parameter	Symbol	Note or test condition	Values			Unit
			Min.	Typ.	Max.	
Rated resistance	R_{25}	$T_{NTC} = 25\text{ °C}$		5		kΩ
Deviation of R_{100}	$\Delta R/R$	$T_{NTC} = 100\text{ °C}, R_{100} = 493\text{ }\Omega$	-5		5	%
Power dissipation	P_{25}	$T_{NTC} = 25\text{ °C}$			20	mW
B-value	$B_{25/50}$	$R_2 = R_{25} \exp[B_{25/50}(1/T_2 - 1/(298,15\text{ K}))]$		3375		K
B-value	$B_{25/80}$	$R_2 = R_{25} \exp[B_{25/80}(1/T_2 - 1/(298,15\text{ K}))]$		3411		K
B-value	$B_{25/100}$	$R_2 = R_{25} \exp[B_{25/100}(1/T_2 - 1/(298,15\text{ K}))]$		3433		K

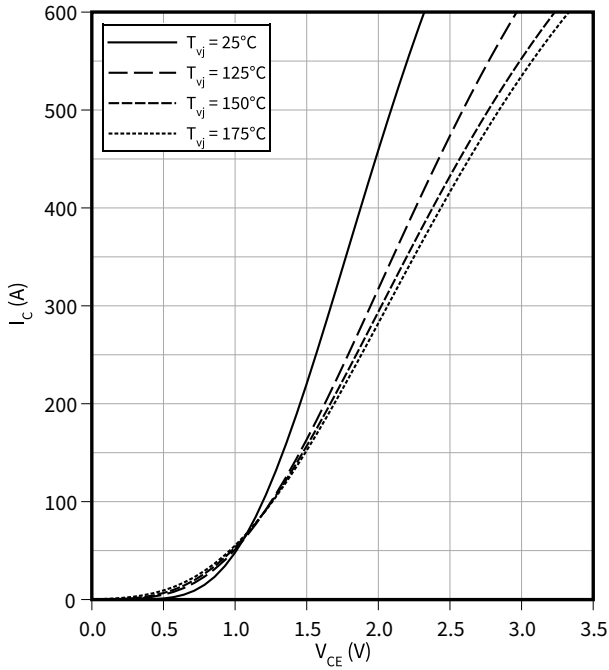
Note: For an analytical description of the NTC characteristics please refer to AN2009-10, chapter 4

5 Characteristics diagrams

Output characteristic (typical), IGBT, T1 / T2

$$I_C = f(V_{CE})$$

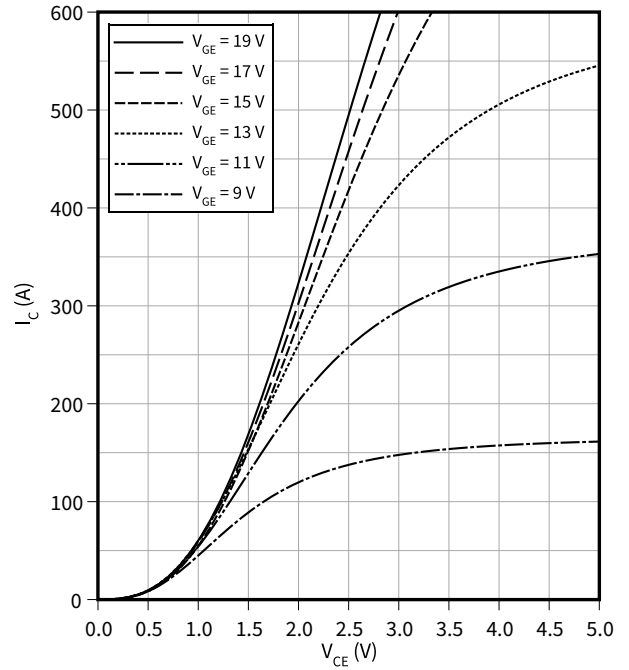
$$V_{GE} = 15 \text{ V}$$



Output characteristic field (typical), IGBT, T1 / T2

$$I_C = f(V_{CE})$$

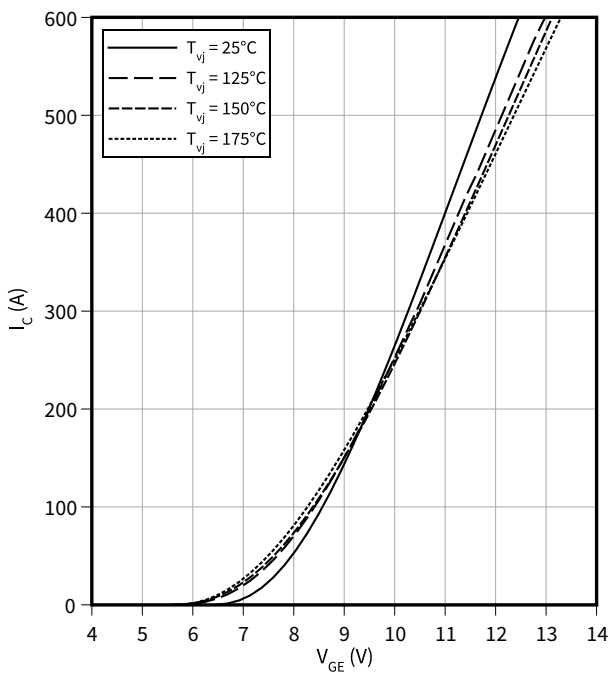
$$T_{vj} = 175 \text{ °C}$$



Transfer characteristic (typical), IGBT, T1 / T2

$$I_C = f(V_{GE})$$

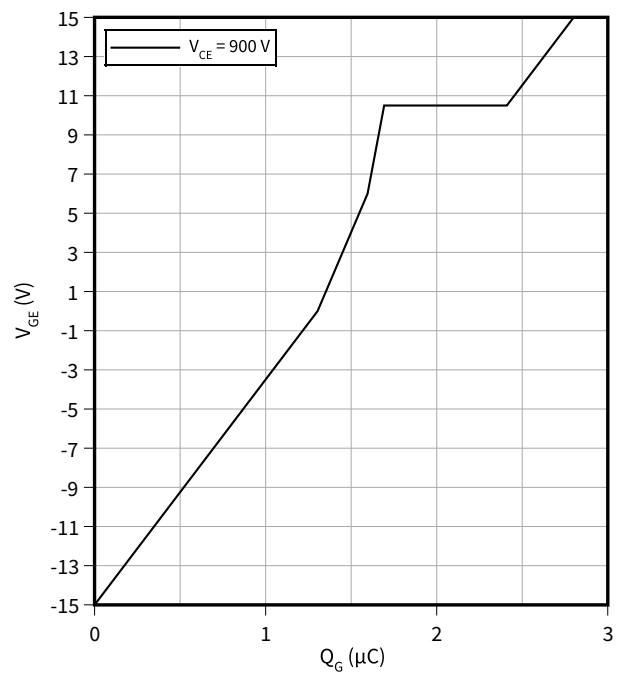
$$V_{CE} = 20 \text{ V}$$



Gate charge characteristic (typical), IGBT, T1 / T2

$$V_{GE} = f(Q_G)$$

$$I_C = 300 \text{ A}, T_{vj} = 25 \text{ °C}$$

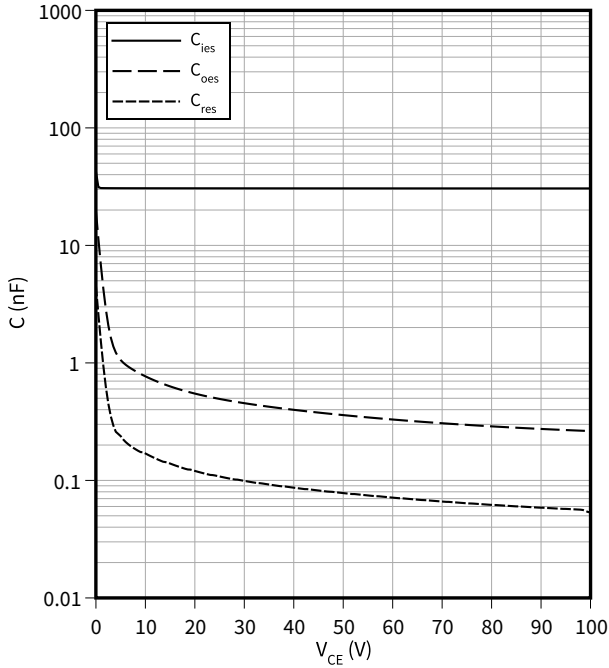


5 Characteristics diagrams

Capacity characteristic (typical), IGBT, T1 / T2

$C = f(V_{CE})$

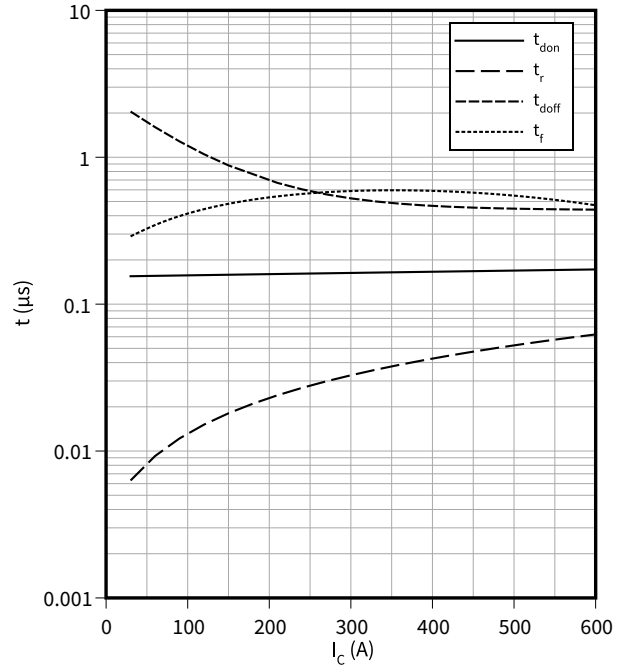
$f = 100 \text{ kHz}, V_{GE} = 0 \text{ V}, T_{vj} = 25 \text{ }^\circ\text{C}$



Switching times (typical), IGBT, T1 / T2

$t = f(I_C)$

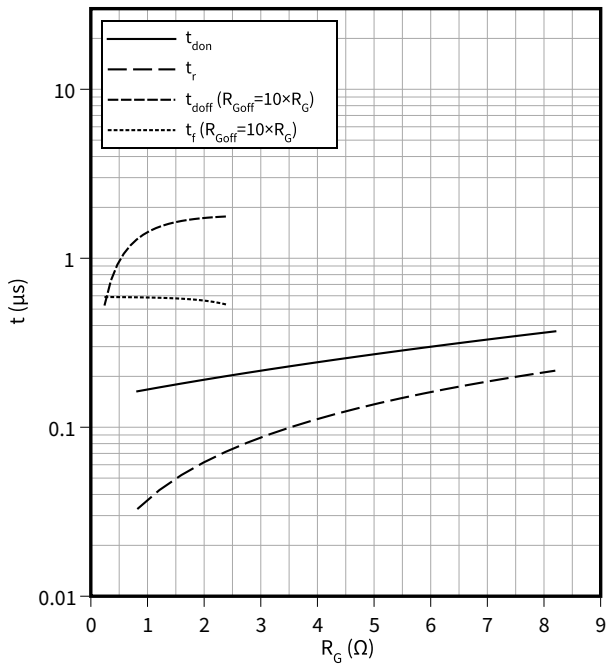
$R_{Goff} = 2.4 \text{ } \Omega, R_{Gon} = 0.82 \text{ } \Omega, V_{CC} = 900 \text{ V}, V_{GE} = \pm 15 \text{ V}, T_{vj} = 175 \text{ }^\circ\text{C}$



Switching times (typical), IGBT, T1 / T2

$t = f(R_G)$

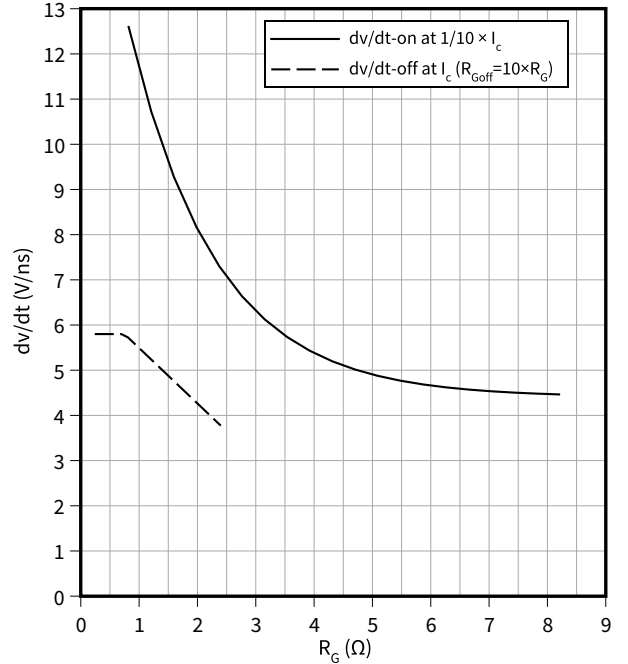
$I_C = 300 \text{ A}, V_{CC} = 900 \text{ V}, V_{GE} = \pm 15 \text{ V}, T_{vj} = 175 \text{ }^\circ\text{C}$



Voltage slope (typical), IGBT, T1 / T2

$dv/dt = f(R_G)$

$I_C = 300 \text{ A}, V_{CC} = 900 \text{ V}, V_{GE} = \pm 15 \text{ V}, T_{vj} = 25 \text{ }^\circ\text{C}$

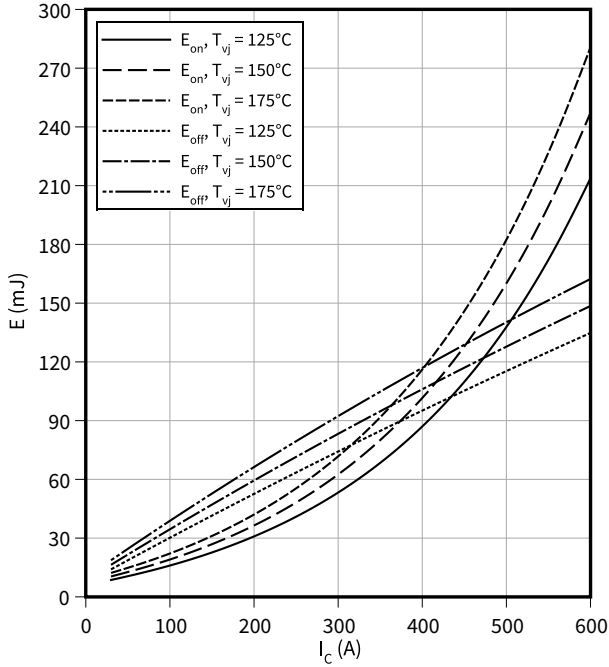


5 Characteristics diagrams

Switching losses (typical), IGBT, T1 / T2

$E = f(I_C)$

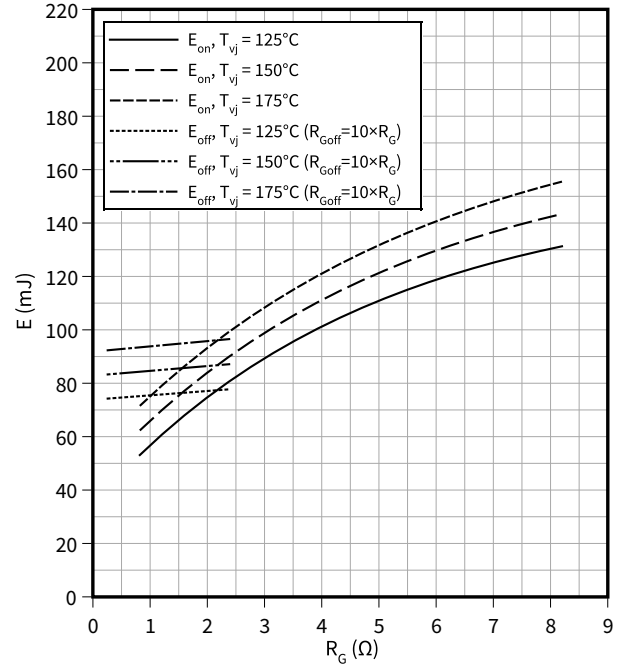
$R_{Goff} = 2.4 \Omega$, $R_{Gon} = 0.82 \Omega$, $V_{CC} = 900 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$



Switching losses (typical), IGBT, T1 / T2

$E = f(R_G)$

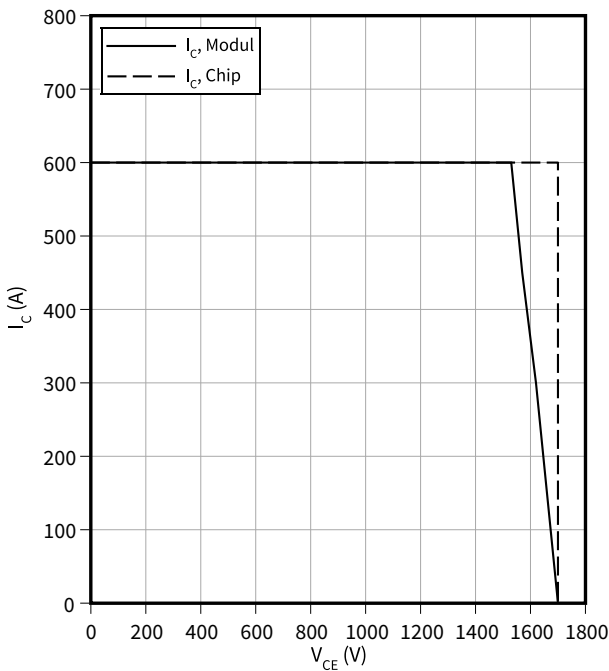
$I_C = 600 \text{ A}$, $V_{CC} = 900 \text{ V}$, $V_{GE} = \pm 15 \text{ V}$



Reverse bias safe operating area (RBSOA), IGBT, T1 / T2

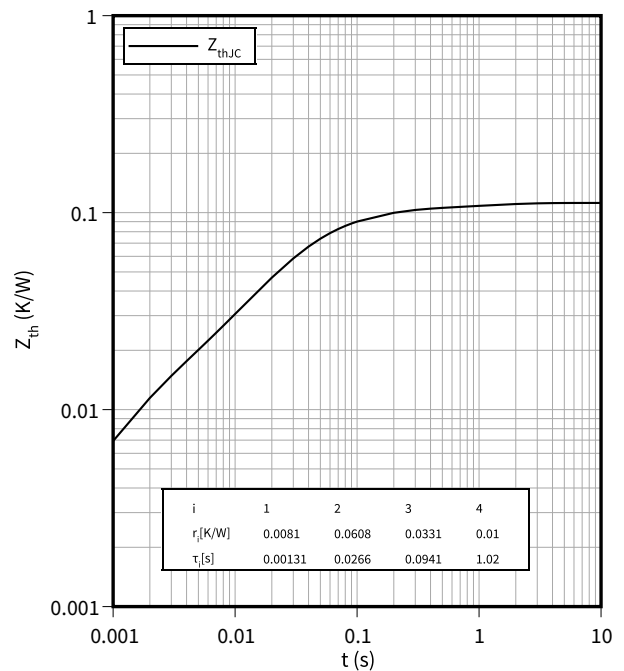
$I_C = f(V_{CE})$

$R_{Goff} = 2.4 \Omega$, $V_{GE} = \pm 15 \text{ V}$, $T_{vj} = 175 \text{ °C}$



Transient thermal impedance, IGBT, T1 / T2

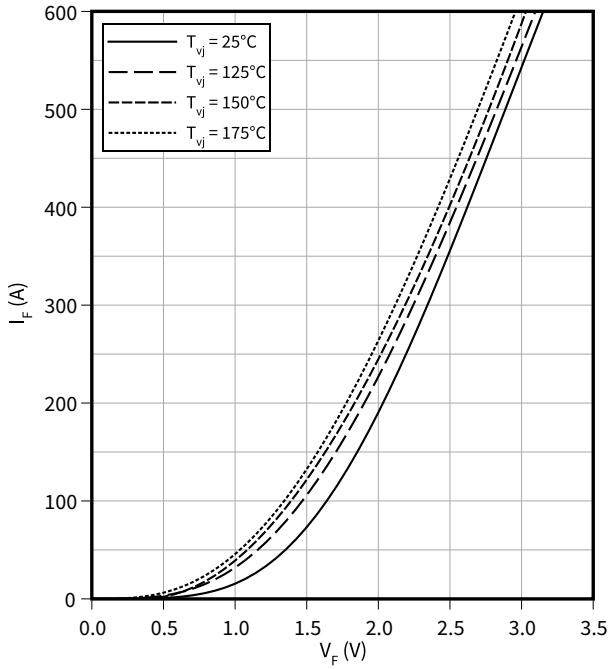
$Z_{th} = f(t)$



5 Characteristics diagrams

Forward characteristic (typical), Diode, D1 / D2

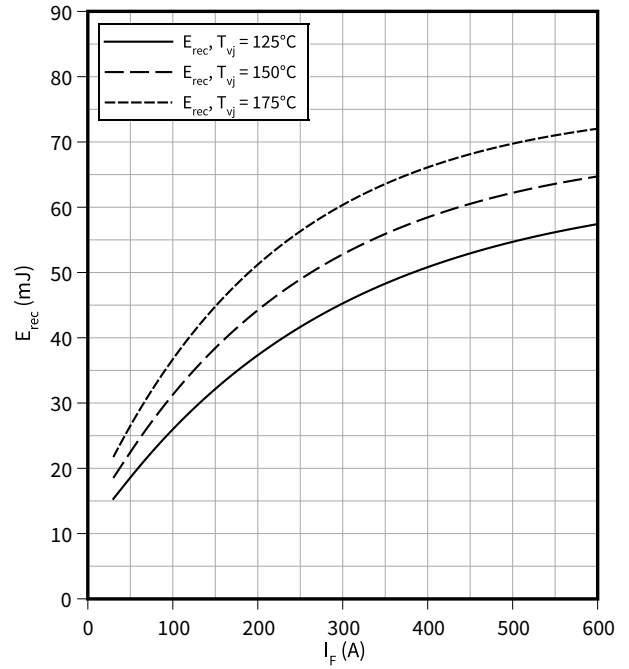
$I_F = f(V_F)$



Switching losses (typical), Diode, D1 / D2

$E_{rec} = f(I_F)$

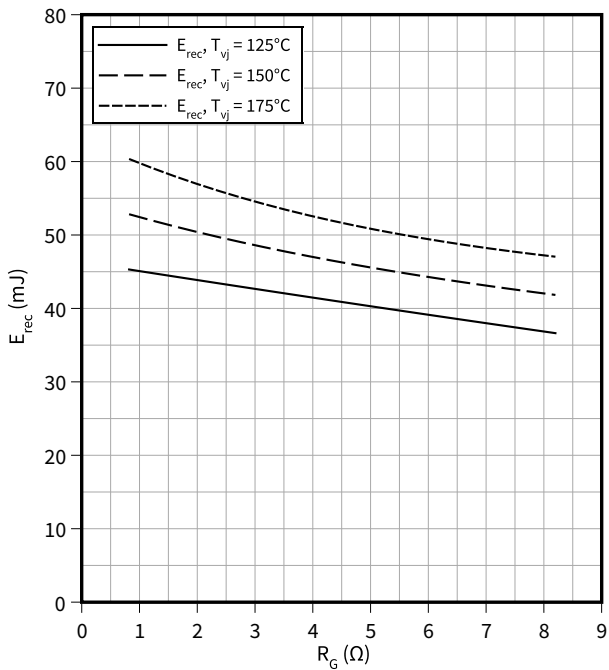
$R_{Gon} = 0.82 \Omega, V_{CC} = 900 V$



Switching losses (typical), Diode, D1 / D2

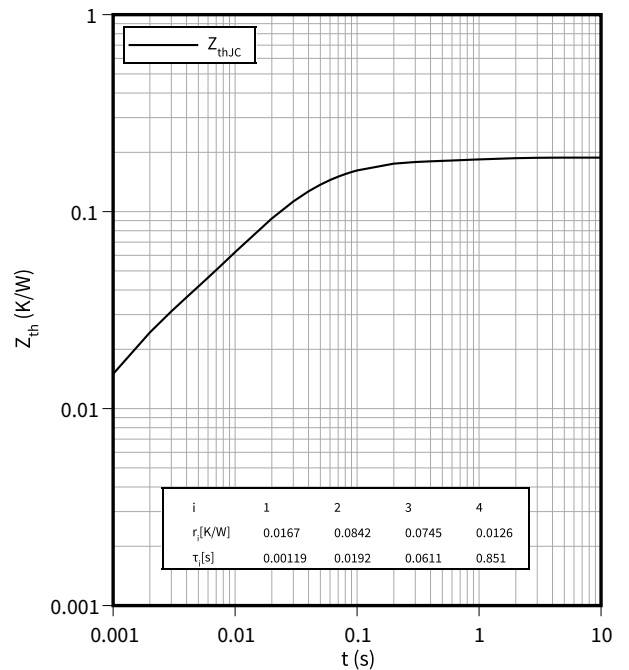
$E_{rec} = f(R_G)$

$I_F = 300 A, V_{CC} = 900 V$



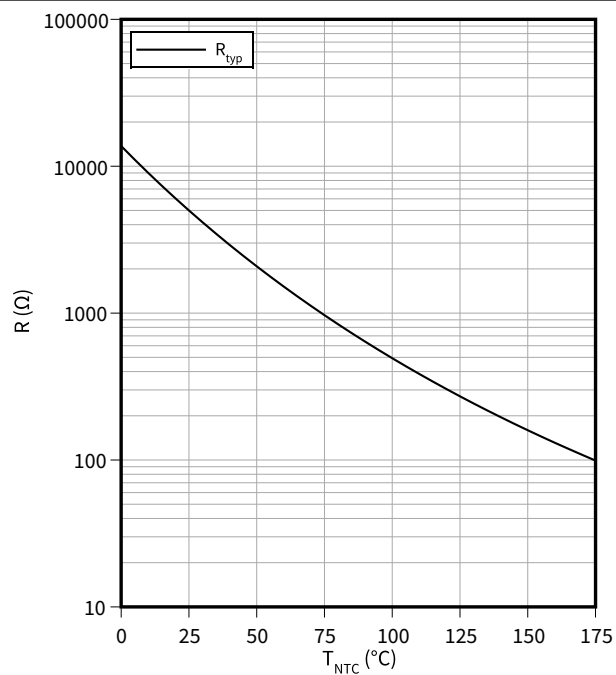
Transient thermal impedance, Diode, D1 / D2

$Z_{th} = f(t)$



Temperature characteristic (typical), NTC-Thermistor

$$R = f(T_{NTC})$$



6 Circuit diagram

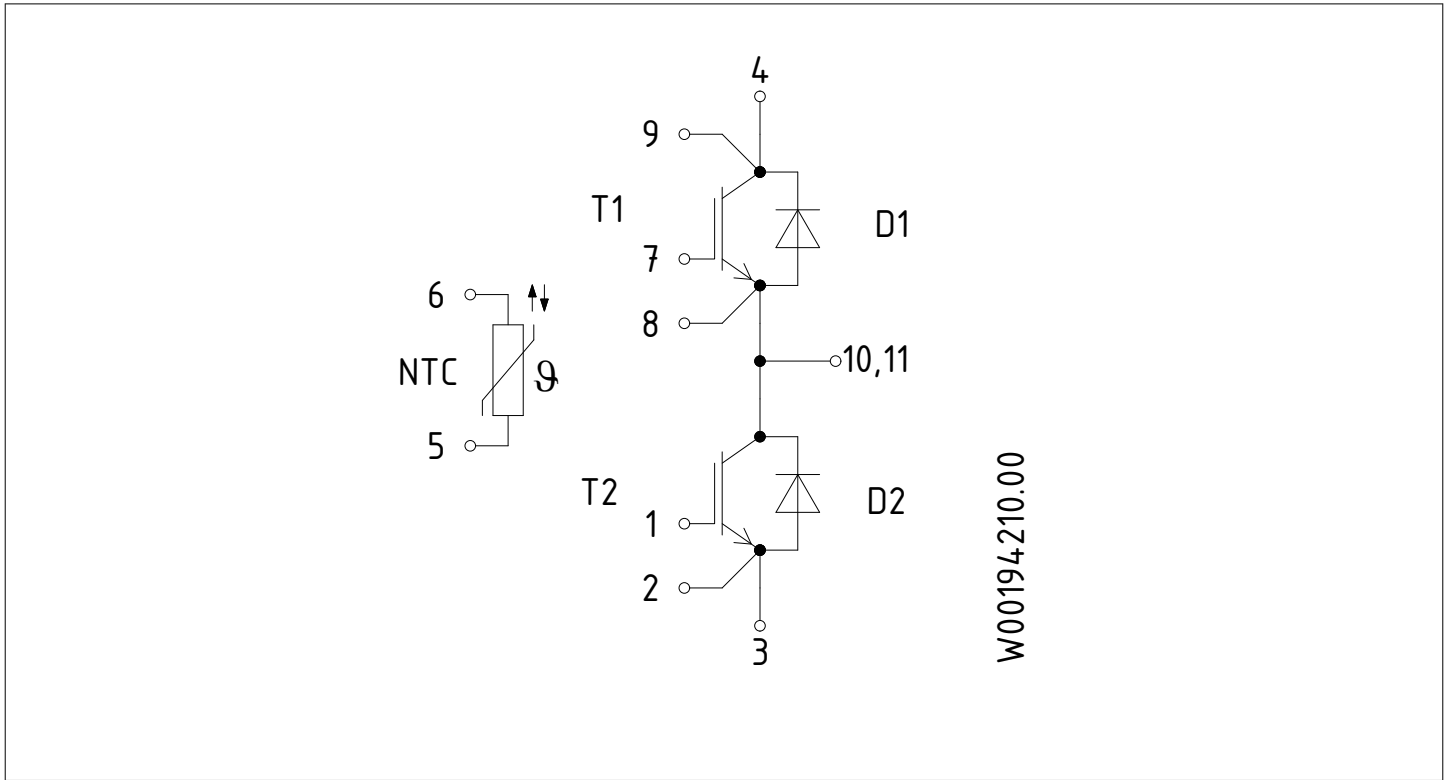


Figure 1

7 Package outlines

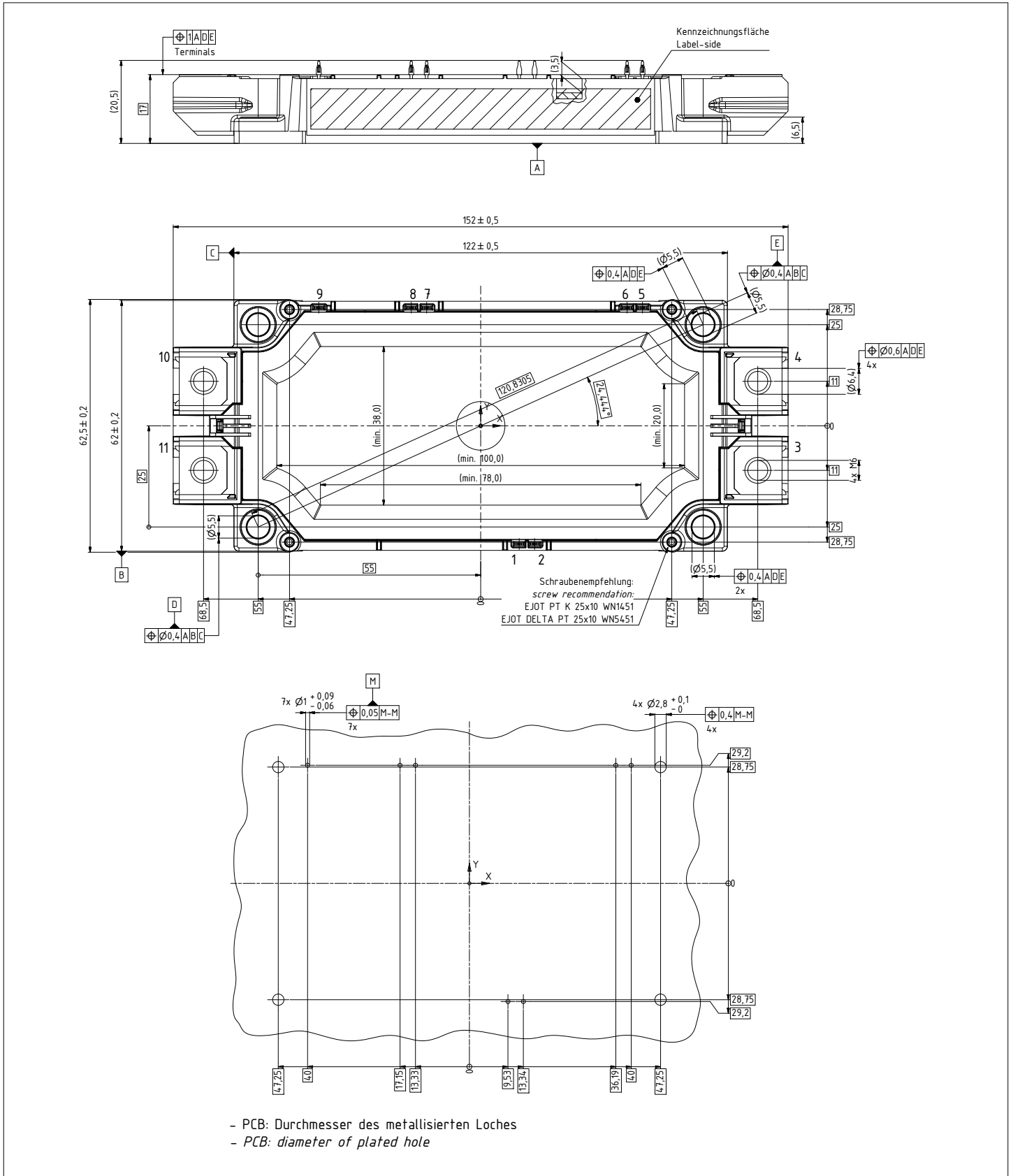


Figure 2

8 Module label code


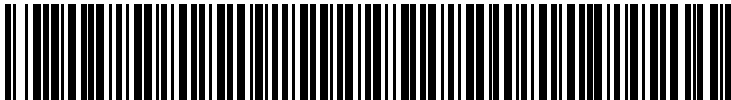
Module label code			
Code format	Data Matrix	Barcode Code128	
Encoding	ASCII text	Code Set A	
Symbol size	16x16	23 digits	
Standard	IEC24720 and IEC16022	IEC8859-1	
Code content	Content	Digit	Example
	Module serial number	1 - 5	71549
	Module material number	6 - 11	142846
	Production order number	12 - 19	55054991
	Date code (production year)	20 - 21	15
	Date code (production week)	22 - 23	30
Example			
	71549142846550549911530		71549142846550549911530

Figure 3

Revision history

Document revision	Date of release	Description of changes
0.10	2023-04-06	Preliminary datasheet
1.00	2023-08-07	Final datasheet

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Document reference

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